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**Integrated chip package structure using organic substrate and method of
manufacturing the same**

Appl. No. : 10/055,499 Confirmation No. 7456
Applicant : Jin-Yuan Lee,
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TC/A.U. : 2891
Examiner : THAI, LUAN C
Docket No. : MEGP0012USA
Customer No. : 27765

Commissioner for Patents
P.O. Box 1450
Alexandria VA 22313-1450

AMENDMENT

5 Sir:

The Final Office Action mailed Nov. 30, 2007 has been carefully considered. In response thereto, please enter the following amendments and consider the remarks, as follows:

10 Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 18 of this paper.